IPC ASSOCIATION CONN ELECTRONICS INDU	© Copyright 2005. I	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both This clevel	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Form Typ Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
upplier Info	formation						·								
Company name*			Company ur	Company unique ID			Unique ID Authority					Response Date*			
nsemi											2024-05-16				
Contact Name			Title - Contact			Pho	Phone - Contact*				Email - Contact*				
Product-Env-S	Stewards		Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com				
uthorized Rep	presentative*		Title - Representative			Pho	Phone - Representative*				Email - Representative*				
Product-Env-S	Stewards		Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com				
Requ	Requester Item Number		Mfr Item Number Mfr Item Name			Effecti		Version	Ma	Manufacturing Site		Weight*	UOM	Unit Type	
		NCP1612	P1612A3DR2G Enhanced, High-Effic		ficiency Power Fact	or 202	24-05-16	PH1			74.7	mg	Each		
Ianufacturi	ing Proccess Informa	tion								,					
Terminal Plating / Grid Array Material Terminal Ba			erminal Base	ninal Base Alloy J-STD-020 MSL Rating Peak Process Body Te					erature	Max Time at Peak	Tempera	ture Numb	er of Reflow Cyc	eles	
Matte Tin (Sn) - annealed C			CU Alloy	1			260	C		30	secon	nds 3			
omments															
vel 1 - maximı	um time at peak temperatı	ure during sol	dering is 10	30 seconds											
or more infort	mation regarding material	composition	please refer t	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	eous Material Weight Unit o		Level	evel Substance		Exempt	Weight	Unit of Measure
Die	1.24	mg	Supplier	Silicon (Si)	7440-21-3		1.24	mg
Die Attach	0.1	mg	Supplier	Silver (Ag)	7440-22-4		0.075	mg
			Supplier	Epoxy resins	129915-35-1		0.025	mg
Lead Frame	15.95		Supplier	Silver (Ag)	7440-22-4		0.335	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0319	mg
			Supplier	Iron (Fe)	7439-89-6		0.3988	mg
			Supplier	Copper (Cu)	7440-50-8		15.1844	mg
Mold Compound-Black	55.41			Epoxy resin	proprietary data		2.7705	mg
			Supplier	Phenolic Resin	Proprietary Data		2.7705	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.1082	mg
			Supplier	Carbon Black (C)	1333-86-4		0.277	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		48.4837	mg
Plating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond - Au	0.11	mg	Supplier	Gold (Au)	7440-57-5		0.11	mg